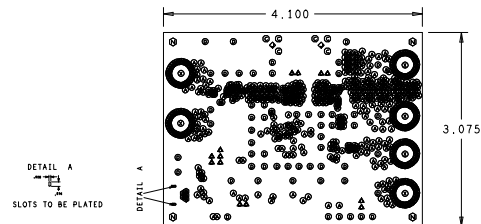


NOTE: All VIAS to be TENTED. NO exposed copper pads on any VIAS top or bottom Except VIAS in SMT pads.



NOTES:

1. THIS IS A 4 LAYER BOARD WITH COMPONENTS ON BOTH SIDES.
2. PRINTED CIRCUIT BOARD SHALL BE 2 OUNCE COPPER.
BOARD MATERIA TO BE EXPOXY BASED FR-4.
3. SMOBC SOLDERMASK BOTH SIDES USING GREEN RESIST. IAW IPC-SM-840
4. SILKSCREEN BOTH SIDE(S) USING WHITE NON CONDUCTIVE EPOXY BASED INK. TRIM ALL SILKSCREEN 4mils FROM BARE COPPER
5. MANUFACTURE/FABRICATE TO MEET EU RoHS DIRECTIVE.
ALL MATERIALS AND SOLDERMASK TO BE COMPLIANT TO EU RoHS DIRECTIVE 20002/95/EC
LAMINATE AND RESIN MATERIAL PARAMETERS
Tg > 170 C
Td > 294 C
6. ELECTROLESS NICKEL GOLD OR IMMERSION GOLD BOARD FINISH.
7. MINIMUM TRACE WIDTH 8 MILS/ SPACE 6 MILS

DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
•	10.0	PLATED	716
•	28.0	PLATED	5
•	37.0	PLATED	6
•	40.0	PLATED	56
•	41.0	PLATED	13
•	93.0	PLATED	2
•	155.0	PLATED	6
•	128.0	NON-PLATED	4
-	76.0x28.0	PLATED	2

Drawn By: MARGARET SAVIEO	Date Drawn: 12-07-15	Engineer: L. Zhao
Released By:	Date Released:	ISL9237EVAL1Z Fabrication Drawing
Updated By:	Date Updated:	
		DATE 15 N/A
		REV. B
intertec	FILENAME: ISL9237EVAL1Z	SHEET 1 of 1